

## Wake Up / Shock Sensor Bottom Sense Model CS6A

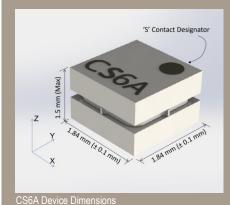
#### **FEATURES:**

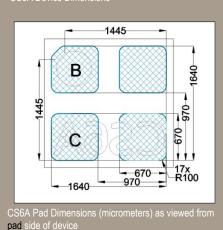
- Small and Lightweight 3.4 mm<sup>2</sup>
- Tape and Reel Packaging

#### **APPLICATIONS:**

- Wake Up Sensing
- Shock Detection







### **Specifications**

#### **OPERATING CHARACTERISTICS:**

| Sensitivity Directions                   | +Z (normal to PCB)                |   |
|--|-----------------------------------|---|
| Contact Acceleration Threshold Range (3) | 20 to 100                         | g |
| Contact Type (2)                         | Normally Open, Non-Latching       | Ū |
| Reset                                    | Automatic with acceleration decay |   |

#### **ELECTRICAL CHARACTERISTICS**

| Contact Resistance (1)< 100  | ohms |
|------------------------------|------|
| Insulation Resistance (min.) | Mohm |
| Breakdown Voltage>100        | VDC  |

#### **ENVIRONMENTAL RATINGS:**

| Operate Temperature Range40 to +85 | $^{\circ}\text{C}$ |
|------------------------------------|--------------------|
| Storage Temperature Range40 to +85 | °C                 |
| PCB/Pad Shear Force>20             | Ν                  |

#### PHYSICAL CHARACTERISTICS:

| Nominal Dimensions (LxWxH) | 1.84 x 1.84 x 1.3 | mm |
|----------------------------|-------------------|----|
| Volume                     |                   |    |
| Mass                       |                   |    |
| ROHS Compliant?            |                   |    |

- (1) Contact resistance is dependent on input pulse acceleration level.
- (2) Electrical connection between pads 'C'(common) & 'B' is normally open and is closed while acceleration is greater than the contact acceleration threshold.
- (3) Contact Acceleration Threshold is approximately 40% greater at an acceleration angle of 45 degrees w.r.t. the Z axis

Note that the information on this data sheet is for reference only.

As each application may have unique requirements, please verify the specifications as well as suitability of using our products in your applications by consulting our engineering department.

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"When Power & Size Are Not An Option"

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